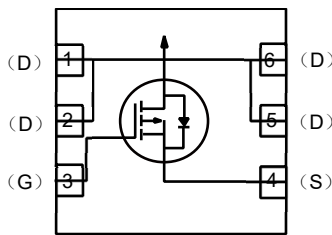


## Description

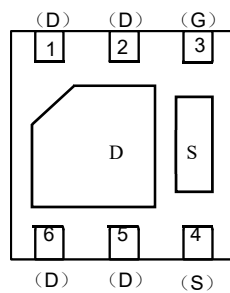
The enhancement mode MOS is extremely high density cell and low on-resistance.

MOSFET Product Summary		
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (mΩ)	I <sub>D</sub> (A)
-30	21 @ V <sub>GS</sub> =-4.5V	-9

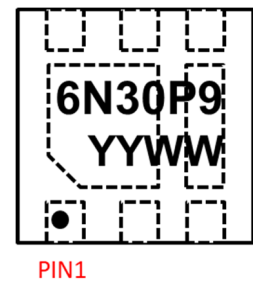
Internal structure



Bottom View



Marking



## Absolute maximum rating@25°C

Rating	Symbol	Value	Units
Drain-Source Voltage	V <sub>DS</sub>	-30	V
Gate-Source Voltage	V <sub>GS</sub>	±12	V
Drain Current	Continuous T <sub>A</sub> =25°C	I <sub>D</sub>	-9 A
	Pulsed T <sub>A</sub> =70°C	I <sub>D</sub>	-36 A
Total Power Dissipation	T <sub>A</sub> =25°C	P <sub>D</sub>	2.4 W
	T <sub>A</sub> =125°C	P <sub>D</sub>	0.9 W
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

## Thermal Characteristics

Parameter	Symbol	Max.	Units
Thermal Resistance, Junction to Ambient (Note 1)	R <sub>θJA</sub>	52	°C/W
Thermal Resistance, Junction to Ambient (Note 2)	R <sub>θJA</sub>	145	
Thermal Resistance, Junction to Case	R <sub>θJC</sub>	6.9	

## Electrical characteristics per line@25°C ( unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Drain-Source Breakdown Voltage	$BV_{DSS}$	$I_D = -250\mu A, V_{GS} = 0V$	-30	-	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -30V, V_{GS} = 0V$	-	-	-1.0	$\mu A$
Gate-to-Source Forward Leakage	$I_{GSS}$	$V_{GS} = \pm 12V$	-	-	$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-0.6	-1.0	-1.5	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = -4.5V, I_D = -5.5A$	-	21	28	m $\Omega$
		$V_{GS} = -2.5V, I_D = -5A,$	-	28	40	m $\Omega$
Maximum Body-Diode Continuous Current	$I_s$	-	-	-	2	A
Forward Trans conductance	$g_{FS}$	$V_{DS} = -5V, I_D = -9A$	21	-	-	S
Total Gate Charge	$Q_g$	$I_D = -9A, V_{DD} = -6V,$ $V_{GS} = -4.5V$	-	13.8	-	nC
Gate-to-Source Charge	$Q_{gs}$		-	2.5		
Gate-to-Drain(Miller) Charge	$Q_{gd}$		-	3.3		
Input Capacitance	$C_{iss}$	$V_{GS} = 0V, V_{DS} = -15V,$ $f = 1MHz$	-	780		pF
Output Capacitance	$C_{DSS}$		-	150		pF
Reverse Transfer Capacitance	$C_{RSS}$		-	98		pF
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = -6.0V, I_D = -9A,$ $V_{GS} = -4.5V, R_{GEN} = 6\Omega,$	-	11	-	ns
Rise Time	$t_r$		-	8	-	
Turn-Off Delay Time	$t_{d(off)}$		-	28.5	-	
Fall Time	$t_f$		-	10.5	-	
Source to Drain Diode Forward Voltage	$V_{SD}$	$V_{GS} = 0V, I_s = -2A$		-0.6	-1.2	V

Note1: Surface mounted on FR4 Board using 1 square inch pad size, 1oz copper

Note2: Surface mounted on FR4 board using minimum pad size, 1oz copper

Note3: Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .

Note4: Guaranteed by design, not subject to production

Typical Characteristics

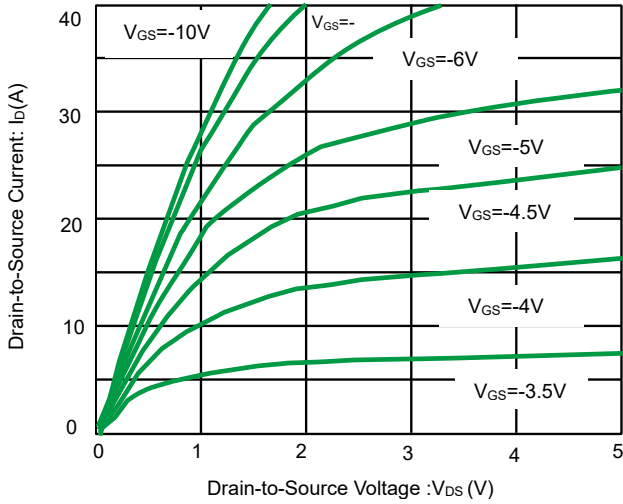


Fig 1. Output Characteristics

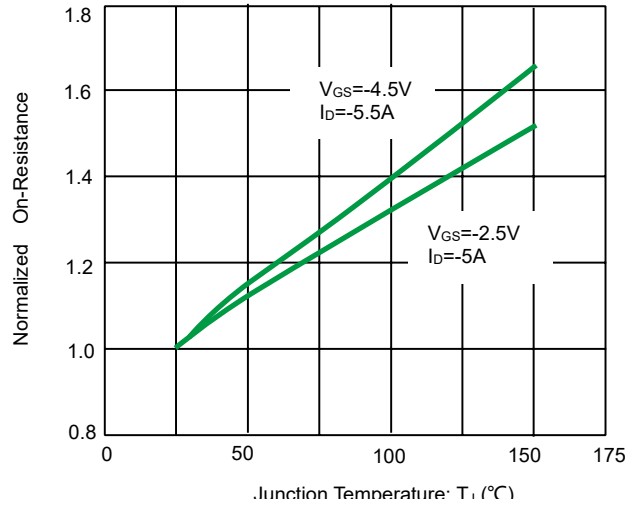


Fig 2. Normalized On-Resistance vs. Junction Temperature

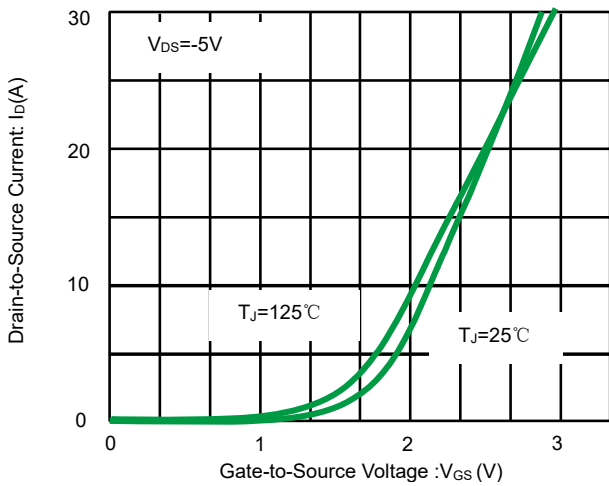


Fig 3. Transfer Characteristics

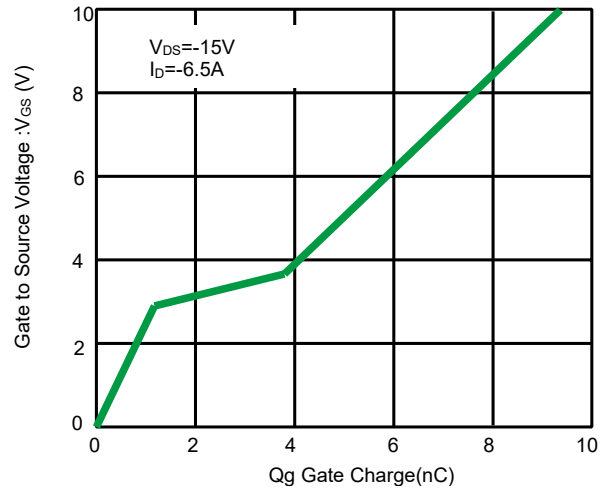


Fig 4. Gate Charge

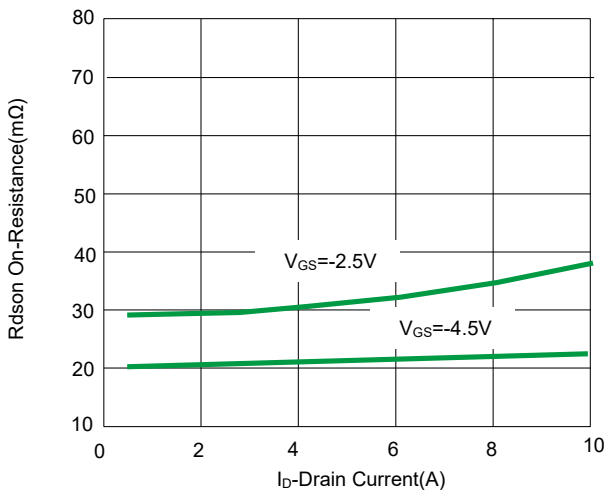


Fig 5. Rdson-Drain Current

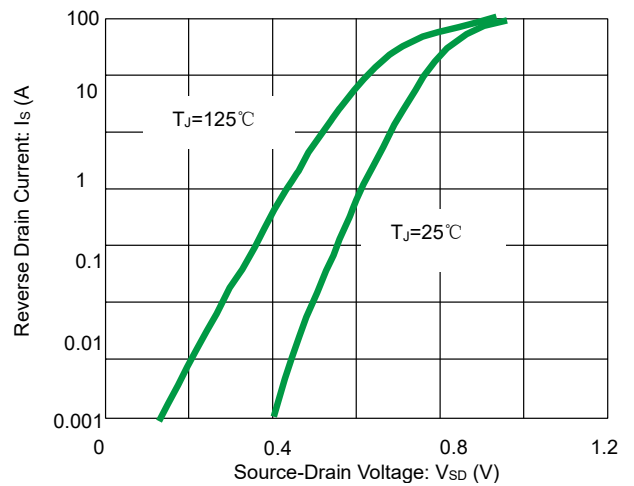


Fig 6. Source to Drain Diode Forward Voltage vs. Source Current

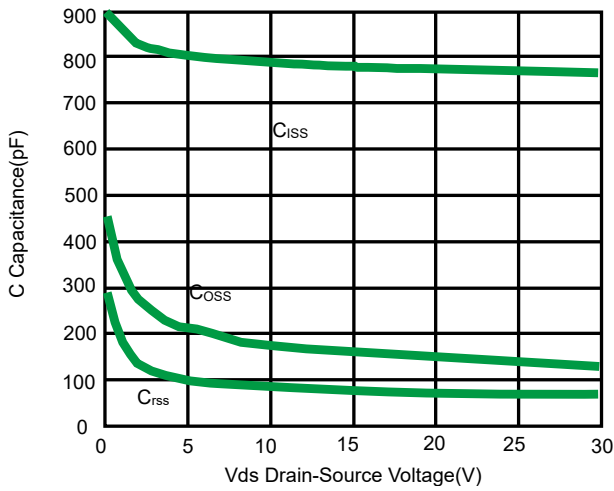


Fig 7. Capacitance vs Vds

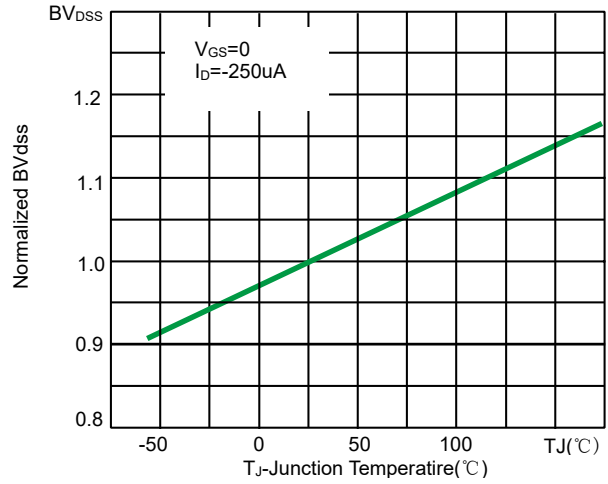


Fig 8. BV<sub>DSS</sub> vs Junction Temperature

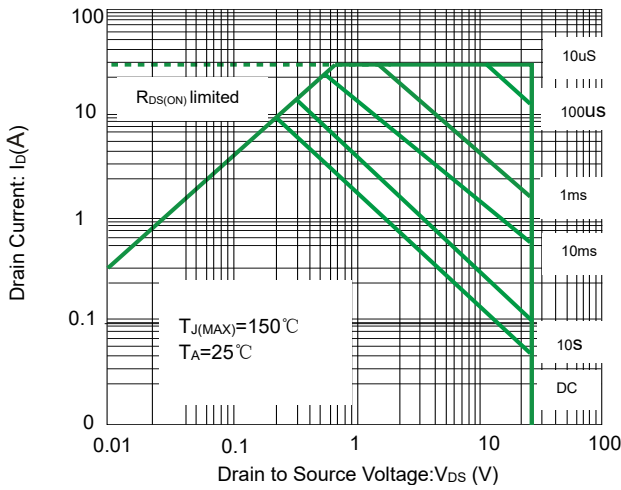


Fig 9. Forward Bias Safe Operating Area

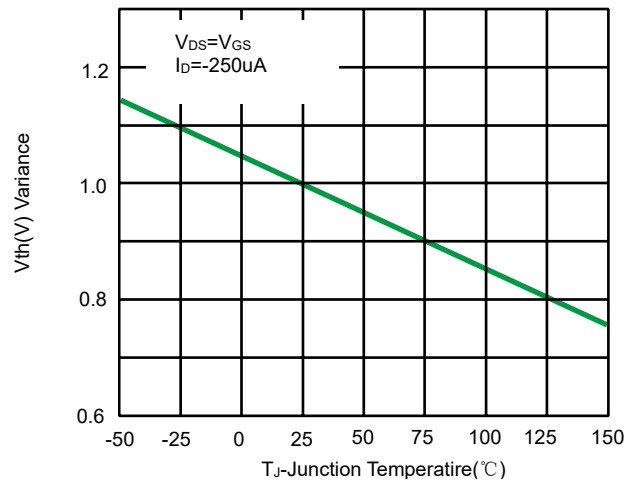


Fig 10. V<sub>GS(th)</sub> vs Junction Temperature

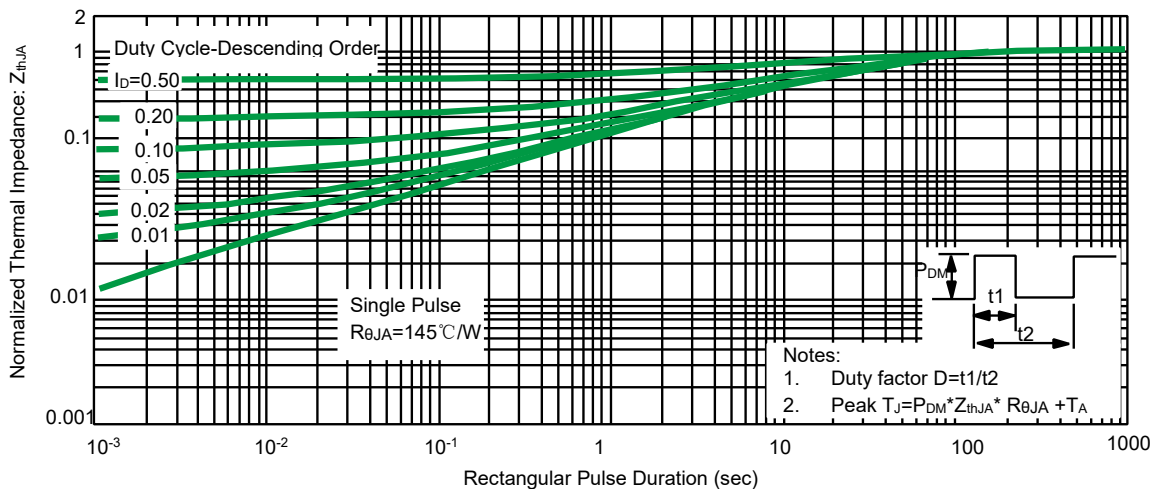
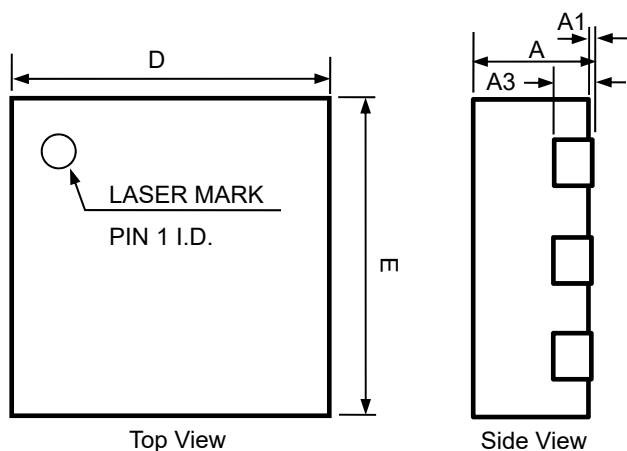
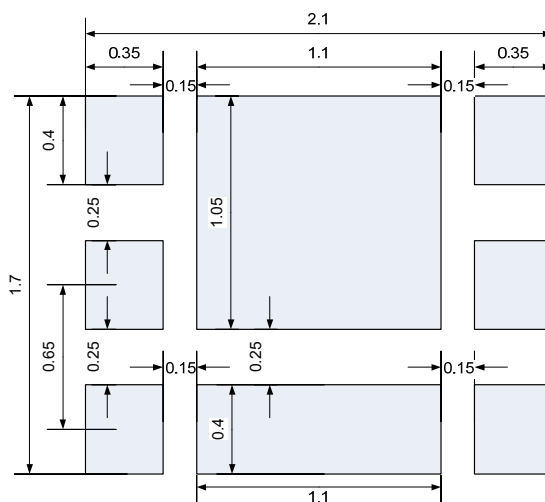
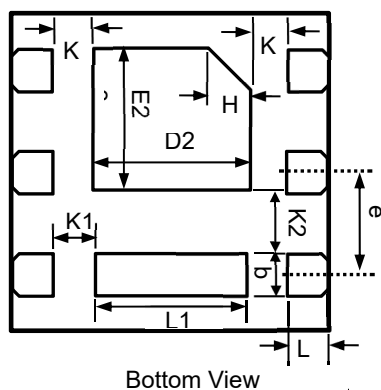


Fig 11. Transient Thermal Response Curve, Junction-to-Ambient

Product dimension (DFN2\*2-6L)



Dim	Millimeters		
	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A3	0.20 Ref.		
b	0.25	0.30	0.35
D	1.90	2.00	2.10
E	1.90	2.00	2.10
D2	0.90	1.00	1.10
E2	0.80	0.90	1.00
e	0.55	0.65	0.75
H	0.25 Ref.		
K	0.15	--	--
K1	0.20	--	--
K2	0.25	--	--
L	0.20	0.25	0.30
L1	0.65	0.75	0.85




Suggested PCB Layout

Ordering information

Device	Package	Reel	Shipping
PPM6N30V9	DFN2*2-6L (Pb-Free)	7"	3000 / Tape & Reel


**IMPORTANT NOTICE**

 and **Prisemi**<sup>®</sup> are registered trademarks of **Prisemi Electronics Co., Ltd (Prisemi)** ,Prisemi reserves the right to make changes without further notice to any products herein. Prisemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Prisemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. “Typical” parameters which may be provided in Prisemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including “Typicals” must be validated for each customer application by customer’s technical experts. Prisemi does not convey any license under its patent rights nor the rights of others. The products listed in this document are designed to be used with ordinary electronic equipment or devices, Should you intend to use these products with equipment or devices which require an extremely high level of reliability and the malfunction of with would directly endanger human life (such as medical instruments, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), please be sure to consult with our sales representative in advance.

Website: <http://www.prisemi.com>

For additional information, please contact your local Sales Representative.

©Copyright 2009, Prisemi Electronics

 **Prisemi**<sup>®</sup> is a registered trademark of Prisemi Electronics.

All rights are reserved.